CM1242-33CP

1-Channel ESD Protection Device in 0201 CSP

Description

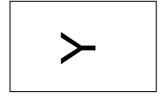
The CM1242-33CP is a 2-bump ESD protection device in 0201 CSP form factor. It is fully compliant with IEC 61000-4-2. The CM1242-33CP is also RoHS II compliant and has a pure tin finish.

Table 1. PIN DESCRIPTIONS

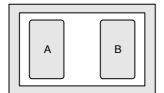
Pin	Description
Α	ESD Channel Pin 1
В	ESD Channel Pin 2

PACKAGE / PINOUT DIAGRAMS

Top View (Bumps Down)



Bottom View (Bumps Up)





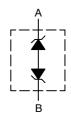
ON Semiconductor®

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WLCSP2 CP SUFFIX CASE 567AV

BLOCK DIAGRAM



MARKING DIAGRAM



Y = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping		
CM1242-33CP	CSP (Pb-Free)	10,000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM1242-33CP

SPECIFICATIONS

Table 2. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Storage Temperature Range	−55 to +150	°C
Operating Temperature Range	-40 to +85	°C
Maximum Input Voltage	±5.5	V

Table 3. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
V _B	Breakdown Voltage	I _F = +10 mA I _F = -10 mA	6.0 -9.0	7.6 -7.6	9.0 -6.0	V
I _{LEAK}	Channel Leakage Current	V _{IN} = ±3.3 V		±0.1	±0.5	μΑ
C _{IN}	Channel Input Capacitance	At 1 MHz, V _{IN} = 0 V	45	55	66	pF
V _{ESD}	ESD Protection Peak Discharge Voltage at any channel input a) Contact Discharge per IEC 61000-4-2 standard b) Air Discharge per IEC 61000-4-2 standard	(Note 2)	±30 ±30			kV
V _{CL}	Channel Clamp Voltage Positive Transients Negative Transients	$I_{PP} = 1 \text{ A, } t_p = 8/20 \ \mu s$		+8.6 -8.6		V
R _{DYN}	Dynamic Resistance Positive Transients Negative Transients	I _{PP} = 1 A, t _p = 8/20 μs		0.4 0.4		Ω

T_A = 25°C unless otherwise specified.
 Standard IEC 61000-4-2 with C_{Discharge} = 150 pF, R_{Discharge} = 330 Ω.

CM1242-33CP

MECHANICAL SPECIFICATIONS

CM1242-33CP Mechanical Specifications

The CM1242-33CP is supplied in a 2-bump Chip Scale Package (CSP). Dimensions are presented below.

Table 4. CSP TAPE AND REEL SPECIFICATIONS

Part Number	Chip Size (mm)	Pocket Size (mm) B ₀ X A ₀ X K ₀	Tape Width W	Reel Diameter	Qty per Reel	P ₀	P ₁
CM1242-33CP	0.60 X 0.30 X 0.275	0.67 X 0.37 X 0.35	8 mm	178 mm (7")	10,000	4 mm	2 mm

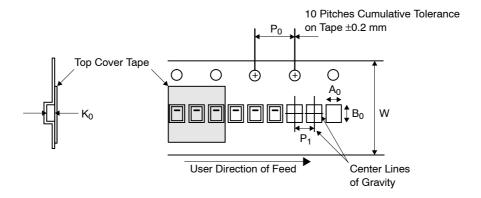


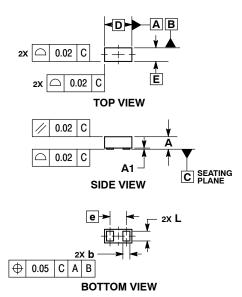
Figure 1. Tape and Reel Mechanical Data





WLCSP2, 0.6x0.3 CASE 567AV ISSUE C

DATE 22 SEP 2017



NOTES:

- DIMENSIONING AND TOLERANCING PER
 ASME V14 5M 1994
- ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS				
DIM	MIN NOM M				
Α	0.250 0.275 0.3				
A1	0.000	0.050			
b	0.140	0.155	0.170		
D	0.570	0.600	0.630		
Е	0.270 0.300 0.33				
е	0.36 BSC				
L	0.190 0.215 0.240				

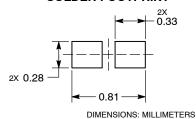
GENERIC MARKING DIAGRAM*



X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED SOLDER FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	WLCSP2, 0.6X0.3		PAGE 1 OF 1	

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